## REMARKS/ARGUMENTS

Examiner J. Diaz is thanked for a complete search and thorough Office Action.

Reconsideration of the objection of claim 21 under 37 CFR 1.75 (c) as being of improper dependent form is respectfully requested for the following reason.

Claim 21 is canceled.

Reconsideration of the rejection of claims 18-19, and 22 under 35 U.S.C. 103(a) as being unpatentable over Cheng, U.S. Patent No. 6,171,976 B1, in view of Applicant's admitted prior art is requested for the following reasons.

The Examiner points out in Final Office Action dated July 6, 2004, page 3, that Cheng fails to teach a 2-micrometer spacing and the formation of a multilevel structure.

The Examiner argues in Final Office Action dated July 6, 2004, page 4, that it is obvious from Cheng in view of the applicant's prior art to make a multilevel planar structure. However, applicant's prior art, page 1, paragraph 2, and page 2, first paragraph, describes a need for making several planar insulating structures on the chip area for integrated circuits, but is silent and does not address a structure that is planar over the kerf areas between an array of chips on a substrate. Only in reviewing the applicant's invention would

one be motivated to make a multilevel planar structure across the substrate, as described by applicant's claim 18.

Therefore the applicant's invention is non-obvious over Cheng in view of the applicant's prior art.

Reconsideration of the rejection of claim 20 under 35 U.S.C. 103(a) as being unpatentable over Cheng (U.S. Patent 6,171,976 B1) in view of applicant's admitted prior art, and further in view of Lou (U.S. Patent 5,759,906) is respectfully requested for the following reasons.

Claim 20 is a dependent claim that does not stand on its own merits but supports the independent claim 18.

It is requested that Examiner Jose R. Diaz call the undersigned Attorney at (845) 452-5863 should there be anything that can be done to help bring this Patent Application to Allowance.

Respectfully submitted,

Stephen B. Ackerman

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